

# C3D08065I

## Silicon Carbide Schottky Diode

### Z-REC™ RECTIFIER

$V_{RRM}$	=	650 V
$I_F (T_c=125^\circ\text{C})$	=	8 A
$Q_c$	=	21 nC

#### Features

- 650-Volt Schottky Rectifier
- Ceramic Package provides 2.5kV isolation
- Zero Reverse Recovery Current
- High-Frequency Operation
- Temperature-Independent Switching Behavior
- Positive Temperature Coefficient on  $V_F$

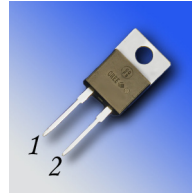
#### Benefits

- Electrically Isolated Package
- Essentially No Switching Losses
- Higher Efficiency
- Reduction of Heat Sink Requirements
- Parallel Devices Without Thermal Runaway

#### Applications

- HVAC
- Switch Mode Power Supplies

#### Package



Part Number	Package	Marking
C3D08065I	Isolated TO-220-2	C3D08065I

#### Maximum Ratings

Symbol	Parameter	Value	Unit	Test Conditions	Note
$V_{RRM}$	Repetitive Peak Reverse Voltage	650	V		
$V_{RSM}$	Surge Peak Reverse Voltage	650	V		
$V_{DC}$	DC Blocking Voltage	650	V		
$I_F$	Continuous Forward Current	15.2 8 7	A	$T_c=25^\circ\text{C}$ $T_c=125^\circ\text{C}$ $T_c=135^\circ\text{C}$	See Fig 3
$I_{FRM}$	Repetitive Peak Forward Surge Current	29 19	A	$T_c=25^\circ\text{C}$ , $t_p=10$ ms, Half Sine pulse $T_c=110^\circ\text{C}$ , $t_p=10$ ms, Half Sine pulse	
$I_{FSM}$	Non-Repetitive Peak Forward Surge Current	69 55	A	$T_c=25^\circ\text{C}$ , $t_p=10$ ms, Half Sine pulse $T_c=110^\circ\text{C}$ , $t_p=10$ ms, Half Sine pulse	
$P_{tot}$	Power Dissipation	48 20	W	$T_c=25^\circ\text{C}$ $T_c=110^\circ\text{C}$	
$T_j$	Operating Junction Range	-55 to +175	$^\circ\text{C}$		
$T_{stg}, T_c$	Storage Temperature and Case Temperature	-55 to +150	$^\circ\text{C}$		
	TO-220 Mounting Torque	1 8.8	Nm lbf-in	M3 Screw 6-32 Screw	

## Electrical Characteristics

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
$V_F$	Forward Voltage	1.5 2.0	1.8 2.4	V	$I_F = 8\text{ A}$ $T_J = 25^\circ\text{C}$ $I_F = 8\text{ A}$ $T_J = 175^\circ\text{C}$	
$I_R$	Reverse Current	12 24	60 220	$\mu\text{A}$	$V_R = 650\text{ V}$ $T_J = 25^\circ\text{C}$ $V_R = 650\text{ V}$ $T_J = 175^\circ\text{C}$	
$Q_C$	Total Capacitive Charge	21		nC	$V_R = 650\text{ V}$ , $I_F = 8\text{ A}$ $di/dt = 500\text{ A}/\mu\text{s}$ $T_J = 25^\circ\text{C}$	
C	Total Capacitance	441 39 33		pF	$V_R = 0\text{ V}$ , $T_J = 25^\circ\text{C}$ , $f = 1\text{ MHz}$ $V_R = 200\text{ V}$ , $T_J = 25^\circ\text{C}$ , $f = 1\text{ MHz}$ $V_R = 400\text{ V}$ , $T_J = 25^\circ\text{C}$ , $f = 1\text{ MHz}$	

Note:

1. This is a majority carrier diode, so there is no reverse recovery charge.

## Thermal Characteristics

Symbol	Parameter	Typ.	Unit
$R_{\theta JC}$	Package Thermal Resistance from Junction to Case	3.1	$^\circ\text{C}/\text{W}$

## Typical Performance

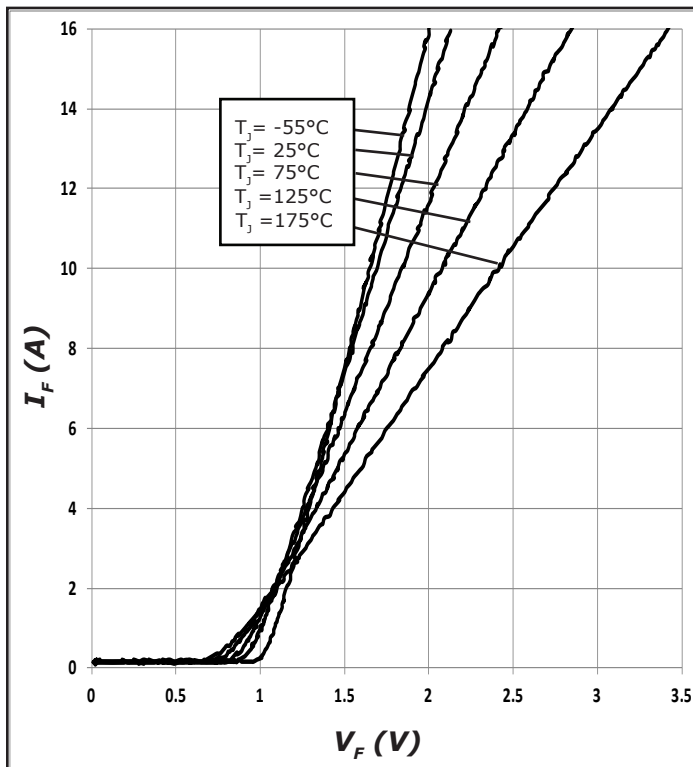


Figure 1. Forward Characteristics

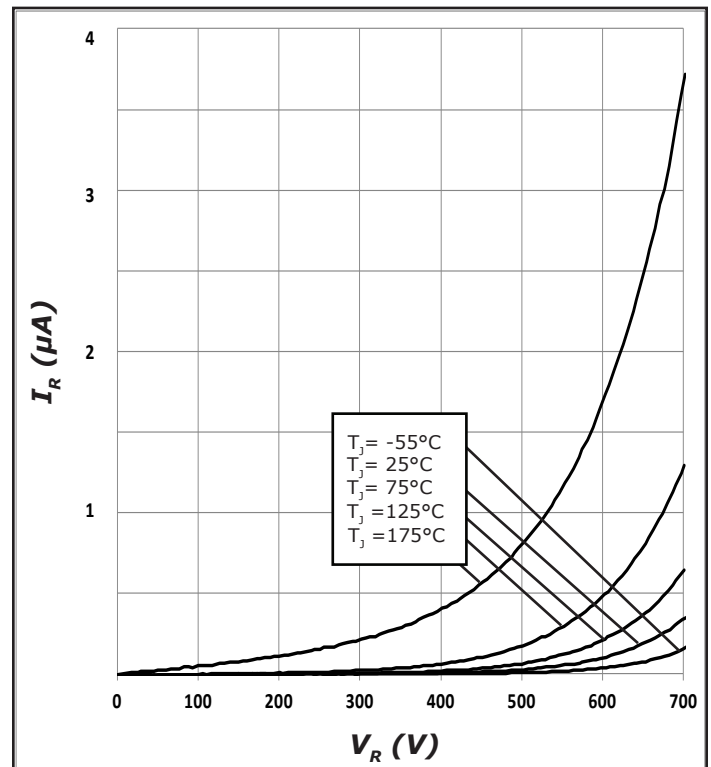


Figure 2. Reverse Characteristics

### Typical Performance

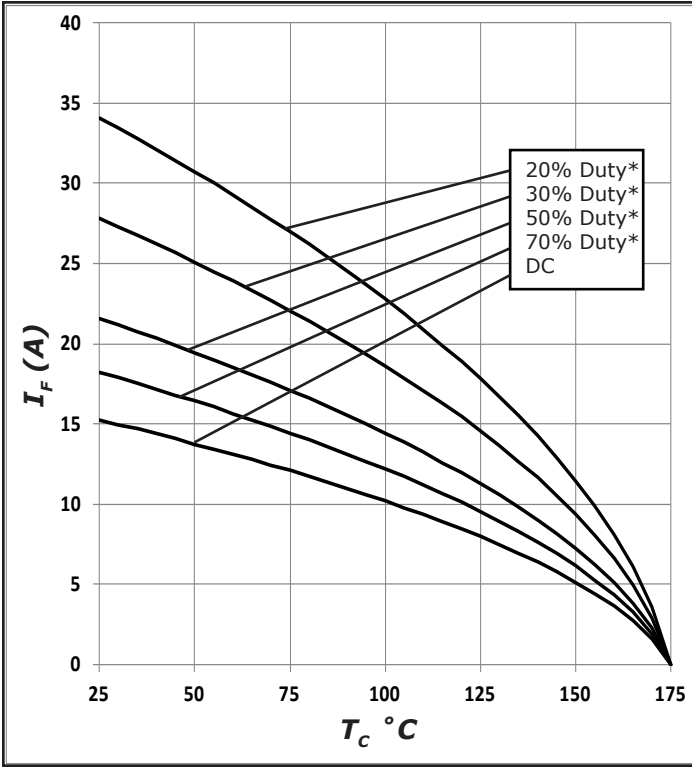


Figure 3. Current Derating

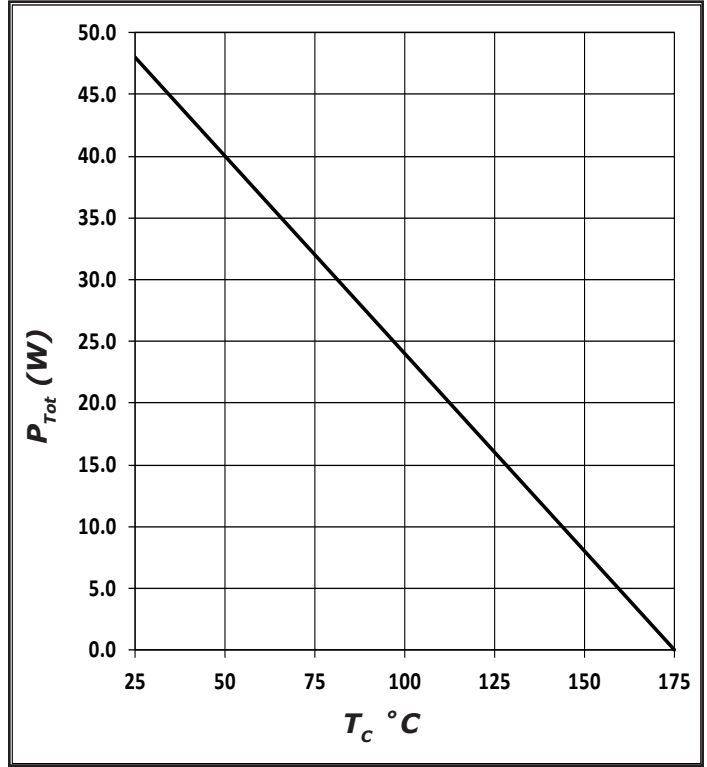


Figure 4. Power Derating

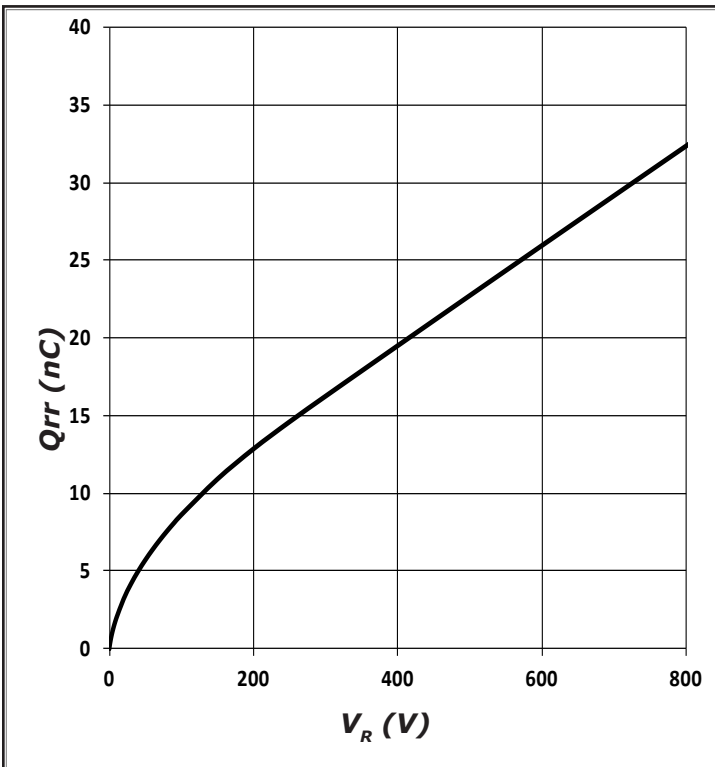


Figure 5. Recovery Charge vs. Reverse Voltage

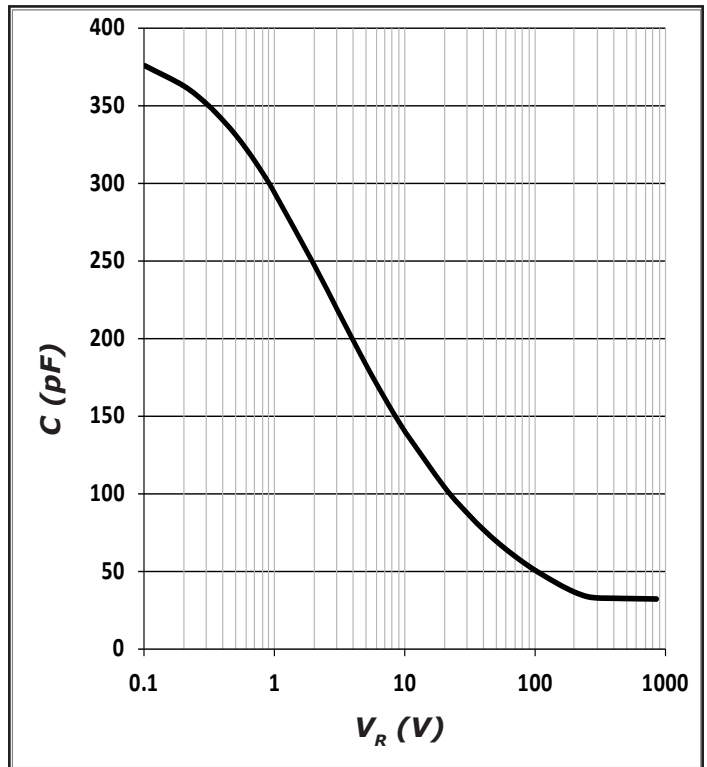


Figure 6. Capacitance vs. Reverse Voltage

## Typical Performance

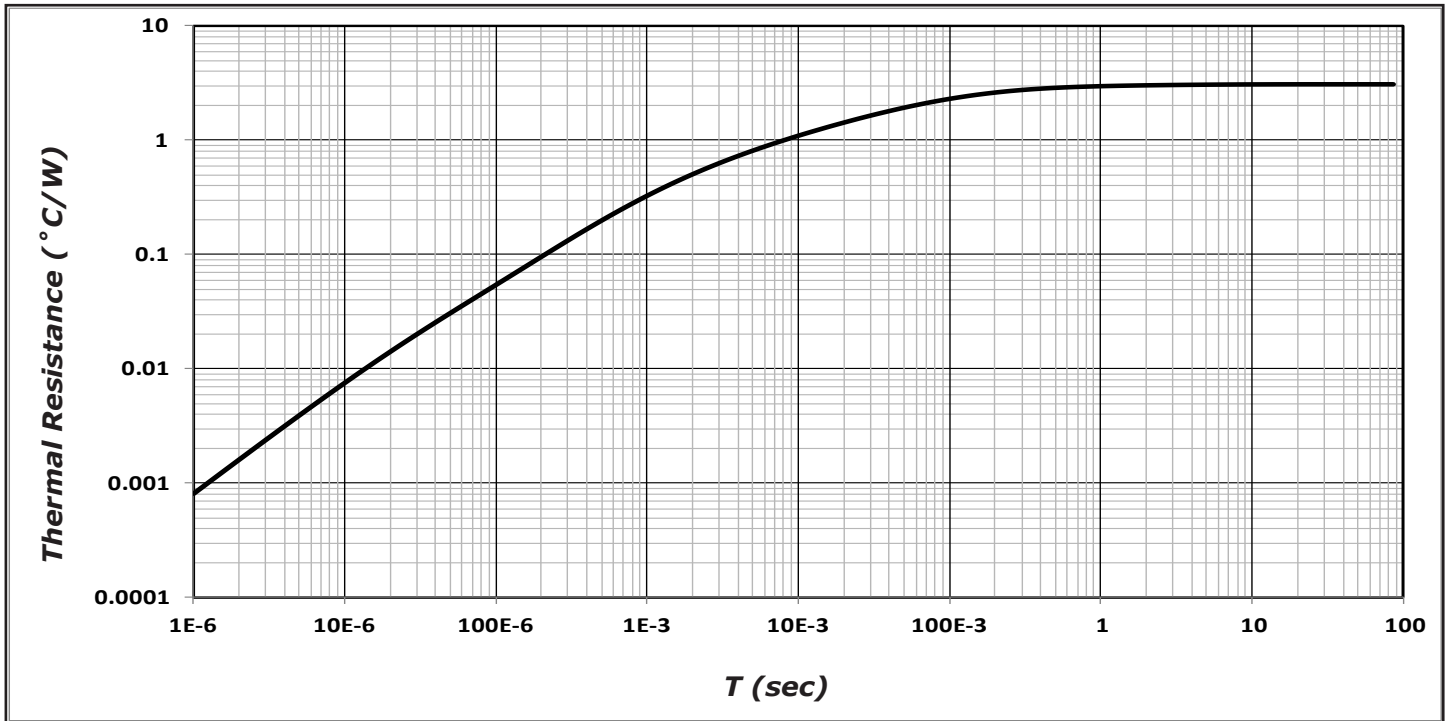
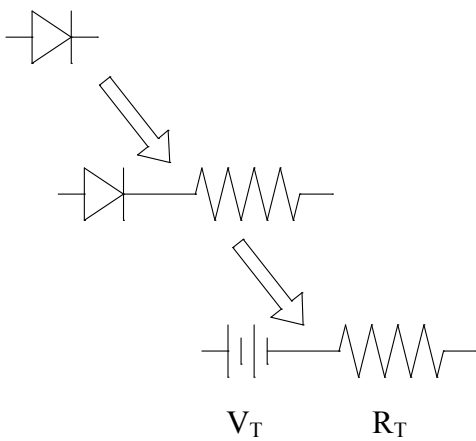


Figure 7. Transient Thermal Impedance

## Diode Model



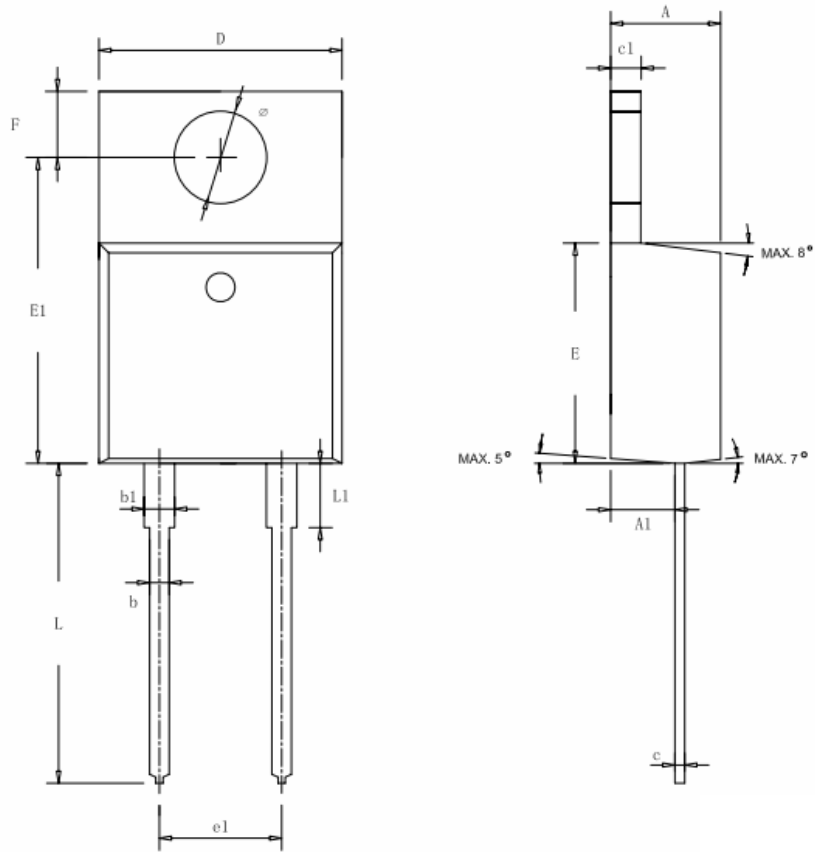
$$V_{fT} = V_T + I_f * R_T$$

$$V_T = 0.98 + (T_j * -1.6 * 10^{-3})$$

$$R_T = 0.04 + (T_j * 0.522 * 10^{-3})$$

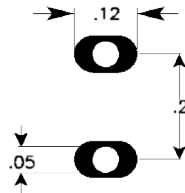
Note:  $T_j$  = Diode Junction Temperature In Degrees Celsius

## Package Dimensions



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min	Max
<b>A</b>	4.420	4.720	1.174	0.186
<b>A1</b>	2.520	2.820	0.099	0.111
<b>b</b>	0.710	0.910	0.028	0.036
<b>b1</b>	1.170	1.370	0.046	0.054
<b>c</b>	0.360	0.460	0.014	0.018
<b>c1</b>	1.170	1.370	0.046	0.054
<b>D</b>	9.950	10.250	0.392	0.404
<b>E</b>	8.930	9.290	0.352	0.366
<b>E1</b>	12.550	12.850	0.494	0.506
<b>e1</b>	4.980	5.180	0.196	0.204
<b>F</b>	2.590	2.890	0.102	0.114
<b>L</b>	13.080	13.480	0.515	0.531
<b>L1</b>	2.470	2.870	0.097	0.113
<b><math>\phi</math></b>	3.790	3.890	0.149	0.153

## Recommended Solder Pad Layout



Measurements shown in inches  
TO-220-2

Part Number	Package	Marking
C3D08065I	Isolated TO-220-2	C3D08065I

Note: Recommended soldering profiles can be found in the applications note here:  
[http://www.cree.com/power\\_app\\_notes/soldering](http://www.cree.com/power_app_notes/soldering)



## Notes

- RoHS Compliance**  
 The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented January 2, 2013. RoHS Declarations for this product can be obtained from your Cree representative or from the Product Documentation sections of [www.cree.com](http://www.cree.com).
- REACH Compliance**  
 REACH substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a Cree representative to insure you get the most up-to-date REACH SVHC Declaration. REACH banned substance information (REACH Article 67) is also available upon request.
- This product has not been designed or tested for use in, and is not intended for use in, applications implanted into the human body nor in applications in which failure of the product could lead to death, personal injury or property damage, including but not limited to equipment used in the operation of nuclear facilities, life-support machines, cardiac defibrillators or similar emergency medical equipment, aircraft navigation or communication or control systems, air traffic control systems, or weapons systems.